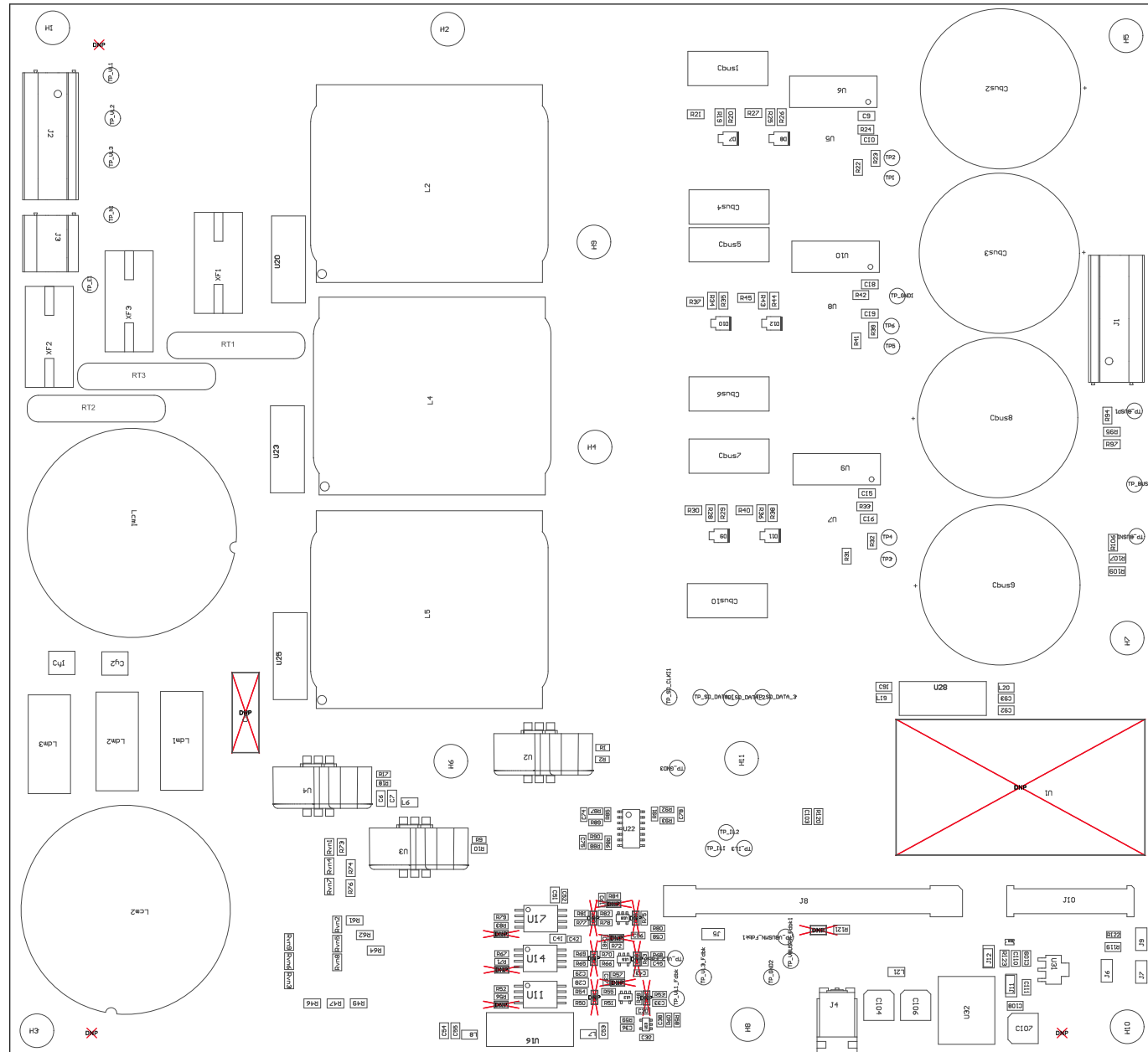
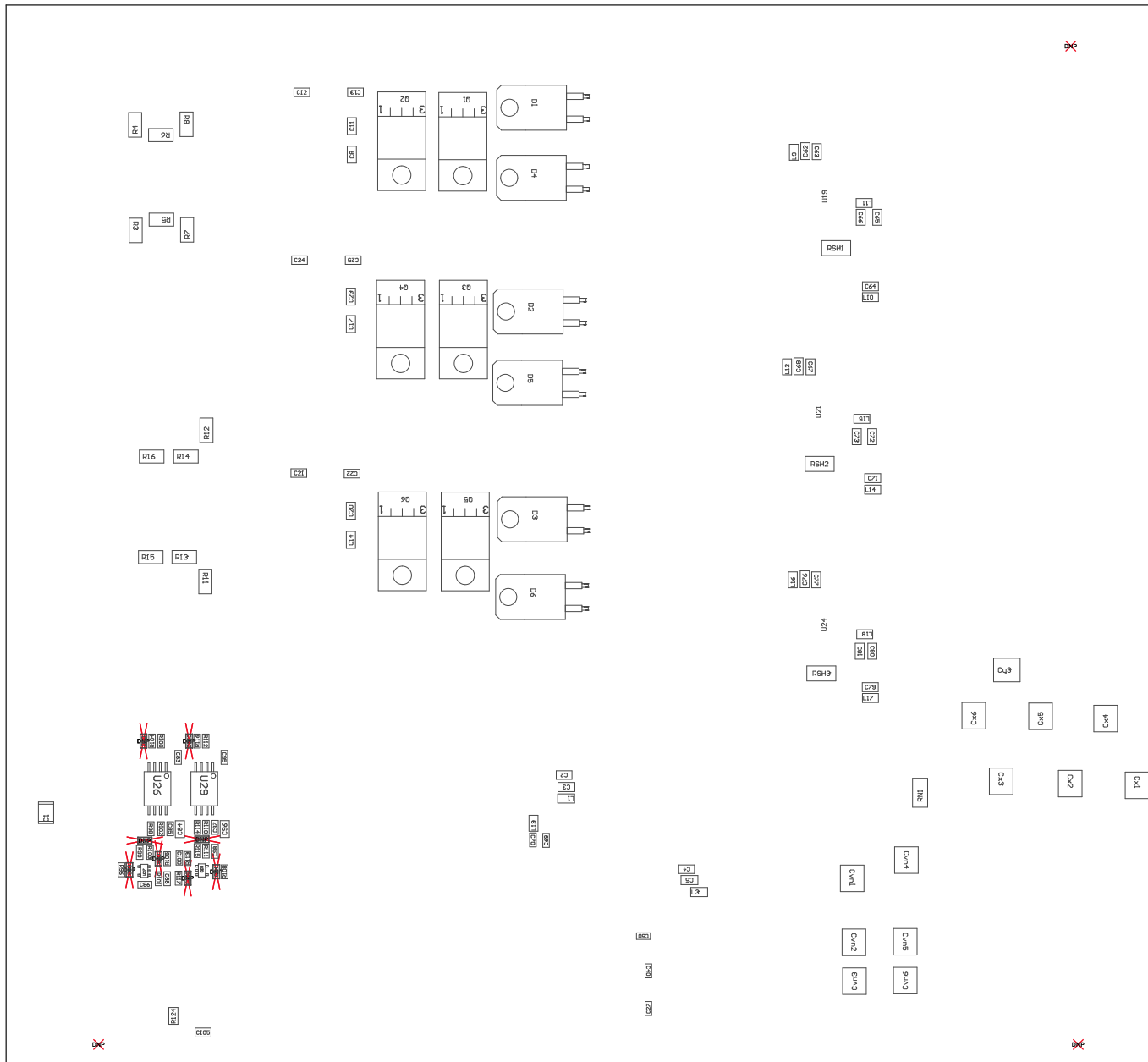


- 221 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- 222 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- 223 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- 224 ■ Mount heatsink HI6 as specified in the mechanical drawing and assembly instructions provided separately.
- 225 ■ Paste SILLI-16 on the heat sink or on the back of D1-06, D1-06, place the insulators HI7-H28 on D1-06 and D1-06
- 226 ■ Place Fuses F1-F3 in fuse holder XF1-XF3



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: MCU011	REV: A	SUN REV: Not In VersionControl
	TID #: TIDM-1000		
PLOT NAME = Top Assembly Drawing	GENERATED : 1/4/2018	9:57:43 AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: MCU011	REV: A	SUN REV: Not In VersionControl
	TID #: TIDM-1000		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 1/4/2018	9:57:46 AM	TEXAS INSTRUMENTS

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